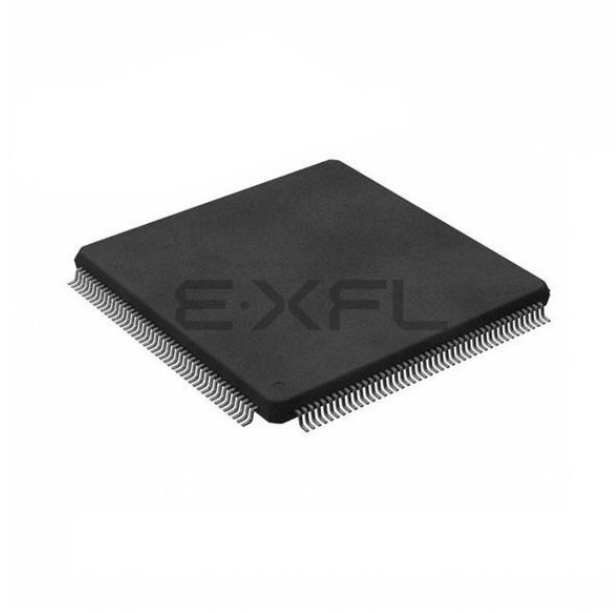


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	180MHz
Connectivity	CANbus, CSIO, EBI/EMI, Ethernet, I²C, LINbus, SD, SmartCard, SPI, UART/USART, USB
Peripherals	DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	153
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 32x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-LQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6e2gm8j0agv2000a

Pin Number		Pin Name	I/O Circuit Type	Pin State Type
LQFP-176	LQFP-144			
127	103	P21	I	K
		ADTG_4		
		SIN0_0		
		INT27_0		
		CROUT_0		
128	104	P20	I	F
		NMIX		
		WKUP0		
129	105	USBVCC1	-	-
130	106	P82	H	R
		UDM1		
131	107	P83	H	R
		UDP1		
132	108	VSS	-	-
133	109	VCC	-	-
134	110	P00	E	G
		TRSTX		
135	111	P01	E	G
		TCK		
		SWCLK		
136	112	P02	E	G
		TDI		
137	113	P03	E	G
		TMS		
		SWDIO		
138	114	P04	E	G
		TDO		
		SWO		
139	-	P90	E	K
		RTO10_1 (PPG10_1)		
		TIOB0_1		
		INT12_1		
		IC0_CLK_1		
140	-	P91	E	K
		SIN5_1		
		RTO11_1 (PPG11_1)		
		TIOB1_1		
		INT13_1		
		IC0_VCC_1		

Module	Pin Name	Function	Pin Number	
			LQFP 176	LQFP 144
Multi-Function Timer 0	DTTI0X_0	Input signal controlling waveform generator outputs RTO00 to RTO05 of Multi-Function Timer 0.	34	29
	DTTI0X_1		8	8
	FRCK0_0	16-bit free-run timer ch 0 external clock input pin	27	22
	FRCK0_1		13	10
	IC00_0	16-bit input capture input pin of Multi-Function Timer 0. ICxx describes channel number.	33	28
	IC00_1		9	9
	IC01_0		32	27
	IC01_1		10	-
	IC02_0		31	26
	IC02_1		11	-
	IC03_0		28	23
	IC03_1		12	-
	RTO00_0 (PPG00_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG00 when it is used in PPG0 output modes.	35	30
	RTO00_1 (PPG00_1)		2	2
	RTO01_0 (PPG00_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG00 when it is used in PPG0 output modes.	36	31
	RTO01_1 (PPG00_1)		3	3
	RTO02_0 (PPG02_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG02 when it is used in PPG0 output modes.	37	32
	RTO02_1 (PPG02_1)		4	4
	RTO03_0 (PPG02_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG02 when it is used in PPG0 output modes.	38	33
	RTO03_1 (PPG02_1)		5	5
	RTO04_0 (PPG04_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG04 when it is used in PPG0 output modes.	39	34
	RTO04_1 (PPG04_1)		6	6
	RTO05_0 (PPG04_0)	Waveform generator output pin of Multi-Function Timer 0. This pin operates as PPG04 when it is used in PPG0 output modes.	40	35
	RTO05_1 (PPG04_1)		7	7

9. Handling Devices

Power-Supply Pins

In products with multiple VCC and VSS pins, respective pins at the same potential are interconnected within the device in order to prevent malfunctions such as latch-up. All of these pins should be connected externally to the power supply or ground lines, however, in order to reduce electromagnetic emission levels, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating.

Be sure to connect the current-supply source with the power pins and GND pins of this device at low impedance. It is also advisable that a ceramic capacitor of approximately 0.1 µF be connected as a bypass capacitor between VCC and VSS near this device.

A malfunction may occur when the power-supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the VCC power supply voltage. As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in VCC ripple (peak-to-peak value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard VCC value, and the transient fluctuation rate does not exceed 0.1V/µs at a momentary fluctuation such as switching the power supply.

Crystal Oscillator Circuit

Noise near the X0/X1 and X0A/X1A pins may cause the device to malfunction. Design the printed circuit board so that X0/X1, X0A/X1A pins, the crystal oscillator (or ceramic oscillator), and the bypass capacitor to ground are located as close to the device as possible.

It is strongly recommended that the PC board artwork be designed such that the X0/X1 and X0A/X1A pins are surrounded by ground plane, as this is expected to produce stable operation.

Evaluate the oscillation introduced by the use of the crystal oscillator by your mount board.

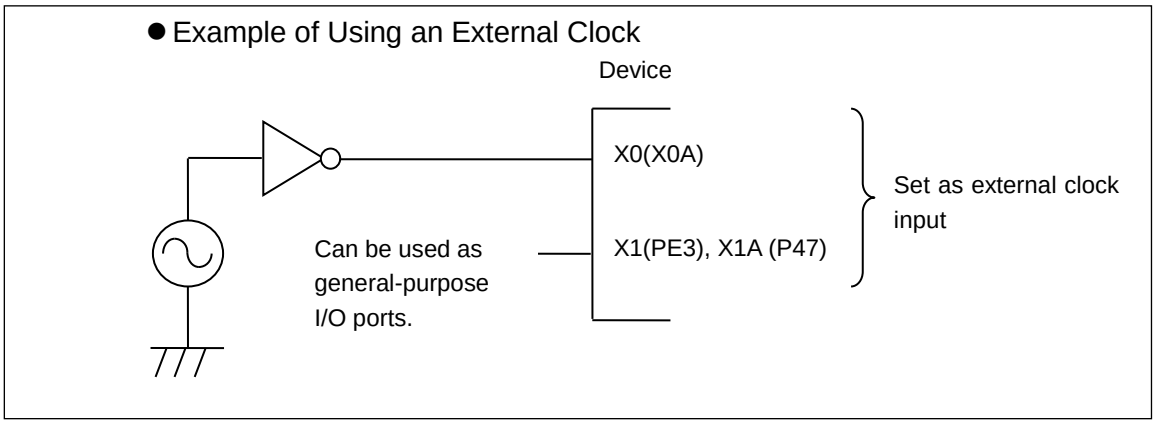
Sub Crystal Oscillator

The sub-oscillator circuit for devices in this family is low gain to keep current consumption low. To stabilize the oscillation, Cypress recommends a crystal oscillator that meets the following conditions:

- Surface mount type
  Size: More than 3.2 mm × 1.5 mm
  Load capacitance: approximately 6 pF to 7 pF
- Lead type
  Load capacitance: approximately 6 pF to 7 pF

Using an External Clock

When using an external clock as an input of the main clock, set X0/X1 to the external clock input, and input the clock to X0. X1(PE3) can be used as a general-purpose I/O port. Similarly, when using an external clock as an input of the sub clock, set X0A/X1A to the external clock input and input the clock to X0A. X1A (P47) can be used as a general-purpose I/O port.

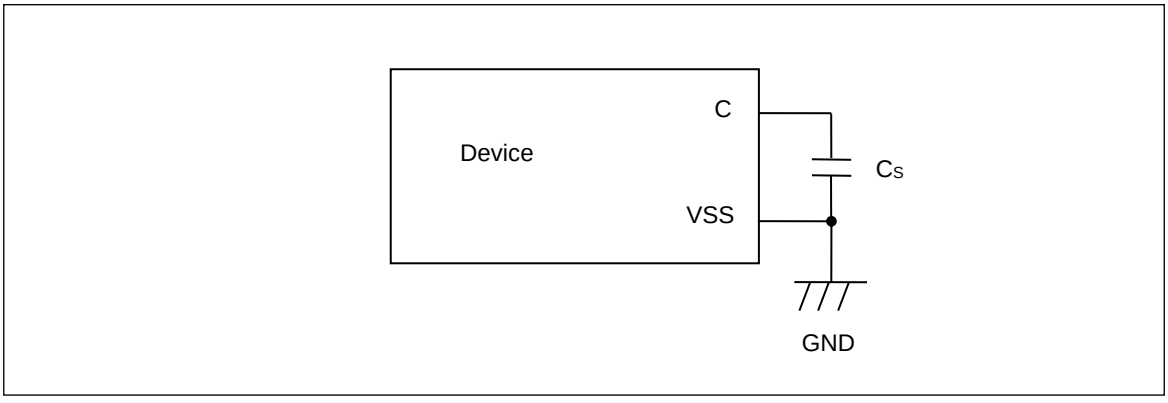


Handling When Using Multi-Function Serial Pin as I²C Pin

If the application uses the multi-function serial pin as an I²C pin, the P-channel transistor of the digital output must be disabled. I²C pins need to conform to electrical limitations like other pins, however, and avoid connecting to live external systems with the MCU power off.

C Pin

Devices in this series contain a regulator. Be sure to connect a smoothing capacitor (C_S) for the regulator between the C pin and the GND pin. Please use a ceramic capacitor or a capacitor of equivalent frequency characteristics as a smoothing capacitor. Some laminated ceramic capacitors have a large capacitance variation due to thermal fluctuation. Please select a capacitor that meets the specifications in the operating conditions to use by evaluating the temperature characteristics of the device. A smoothing capacitor of about 4.7 µF would be recommended for this series.



Mode Pins (MD0)

Connect the MD pin (MD0) directly to VCC or VSS pins. Design the printed circuit board such that the pull-up/down resistance stays low, the distance between the mode pins and VCC pins or VSS pins is as short as possible, and the connection impedance is low when the pins are pulled up/down such as for switching the pin level and rewriting the flash memory data. This is important to prevent the device from erroneously switching to test mode as a result of noise.

List of Pin Behavior by Mode State

Pin Status Type	Function Group	Power-On Reset or Low-Voltage Detection State	INITX Input State	Device Internal Reset State	Run mode or Sleep mode State	Timer mode, RTC mode, or Stop mode State		Deep Standby RTC mode or Deep Standby Stop mode State		Return from Deep Standby mode State
		Power Supply Unstable	Power Supply Stable		Power Supply Stable	Power Supply Stable		Power Supply Stable		Power Supply Stable
		-	INITX=0	INITX=1	INITX=1	INITX=1		INITX=1		INITX=1
		-	-	-	-	SPL=0	SPL=1	SPL=0	SPL=1	-
A	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/internal input fixed at 0	GPIO selected, internal input fixed at 0	Hi-Z/internal input fixed at 0	GPIO selected
	Main crystal oscillator input pin/ external main clock input selected	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input Enabled
B	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/internal input fixed at 0	GPIO selected, internal input fixed at 0	Hi-Z/internal input fixed at 0	GPIO selected
	External main clock input selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/internal input fixed at 0	Maintain previous state	Hi-Z/internal input fixed at 0	Maintain previous State
	Main crystal oscillator output pin	Hi-Z/ internal input fixed at 0/ or input enabled	Hi-Z/ internal input fixed at 0	Hi-Z/ internal input fixed at 0	Maintain previous state while oscillator active/ When oscillation stops*[1], it will be Hi-Z/ Internal input fixed at 0					
C	INITX input pin	Pull-up/ input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled
D	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
E	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/ input enabled	GPIO selected	Hi-Z/ input enabled	GPIO selected

1: Oscillation is stopped at Sub Timer mode, sub CR Timer mode, RTC mode, Stop mode, Deep Standby RTC mode, and Deep Standby Stop mode.

2: Maintain previous state at Timer mode. GPIO selected internal input fixed at 0 at RTC mode, Stop mode.

3: Maintain previous state at Timer mode. Hi-Z/internal input fixed at 0 at RTC mode, Stop mode.

4: It shows the case selected by EPFR14.E_SPLC register.

Table 12-3 Typical and Maximum Current Consumption in Normal Operation (PLL), Code with Data Accessing Running from Flash Memory (Flash 0 Wait-Cycle Mode and Read Access 0 Wait)

Parameter	Symbol	Pin Name	Conditions		Frequency*4	Value		Unit	Remarks
						Typ*1	Max*2		
Power supply current	I_{CC}	VCC	Normal operation *6,*7 (PLL)	*5	72 MHz	54	112	mA	*3 When all peripheral clocks are on
					60 MHz	47	105	mA	
					48 MHz	39	97	mA	
					36 MHz	31	89	mA	
					24 MHz	23	81	mA	
					12 MHz	14	72	mA	
					8 MHz	11	69	mA	
					4 MHz	7.2	65	mA	
				*5	72 MHz	37	95	mA	*3 When all peripheral clocks are off
					60 MHz	33	91	mA	
					48 MHz	28	86	mA	
					36 MHz	23	81	mA	
					24 MHz	17	75	mA	
					12 MHz	11	69	mA	
					8 MHz	8.3	66	mA	
					4 MHz	5.9	63	mA	

1: T_A = +25 °C, V_{CC} = 3.3 V

2: T_J = +125 °C, V_{CC} = 5.5 V

3: When all ports are input and are fixed at 0

4: Frequency is a value of HCLK when PCLK0 = PCLK1 = PCLK2 = HCLK

5: When operating flash 0 wait-cycle mode and read access 0 wait (FRWTR.RWT = 00, FBFCR.SD = 000)

6: With data access to a MainFlash memory.

7: When using the crystal oscillator of 4 MHz (including the current consumption of the oscillation circuit)

12.3.2 Pin Characteristics

(V_{CC} = $USBV_{CC}0$ = $USBV_{CC}1$ = $ETHV_{CC}$ = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
H level input voltage (hysteresis input)	V_{IHS}	CMOS hysteresis input pin, MD0, MD1	-	V_{CC}×0.8	-	V_{CC} + 0.3	V	
				$ETHV_{CC}$×0.8	-	$ETHV_{CC}$ + 0.3	V	
		MADATAxx	V_{CC} > 3.0 V, V_{CC} ≤ 3.6 V,	2.4	-	V_{CC} + 0.3	V	At External Bus
		5V tolerant input pin	-	V_{CC}×0.8	-	V_{SS} + 5.5	V	
		Input pin doubled as I^2C Fm+	-	V_{CC}×0.7	-	V_{SS} + 5.5	V	
		TTL Schmitt input pin	-	2.0	-	$ETHV_{CC}$+0.3	V	
L level input voltage (hysteresis input)	V_{ILS}	CMOS hysteresis input pin, MD0, MD1	-	V_{SS} - 0.3	-	V_{CC}×0.2	V	
				V_{SS} - 0.3	-	$ETHV_{CC}$×0.2	V	
		5V tolerant input pin	-	V_{SS} - 0.3	-	V_{CC}×0.2	V	
		Input pin doubled as I^2C Fm+	-	V_{SS}	-	V_{CC}×0.3	V	
		TTL Schmitt input pin	-	V_{SS} - 0.3	-	0.8	V	
H level output voltage	V_{OH}	4 mA type	V_{CC} ≥ 4.5 V, I_{OH} = - 4 mA	V_{CC} - 0.5	-	V_{CC}	V	
			V_{CC} < 4.5 V, I_{OH} = - 2 mA					
			$ETHV_{CC}$ ≥ 4.5 V, I_{OH} = - 4 mA	V_{CC} - 0.5	-	$ETHV_{CC}$	V	
			$ETHV_{CC}$ < 4.5 V, I_{OH} = - 2 mA					
		8 mA type	V_{CC} ≥ 4.5 V, I_{OH} = - 8 mA	V_{CC} - 0.5	-	V_{CC}	V	
			V_{CC} < 4.5 V, I_{OH} = - 4 mA					
			$ETHV_{CC}$ ≥ 4.5 V, I_{OH} = - 8 mA	$ETHV_{CC}$ - 0.5	-	$ETHV_{CC}$	V	
			$ETHV_{CC}$ < 4.5 V, I_{OH} = - 4 mA					
		12 mA type	V_{CC} ≥ 4.5 V, I_{OH} = - 12 mA	V_{CC} - 0.5	-	V_{CC}	V	
			V_{CC} < 4.5 V, I_{OH} = - 8 mA					
		The pin doubled as USB I/O	$USBV_{CC}$ ≥ 4.5 V, I_{OH} = - 20.5 mA	$USBV_{CC}$ - 0.4	-	$USBV_{CC}$	V	*1
			$USBV_{CC}$ < 4.5 V, I_{OH} = - 13.0 mA					
		The pin doubled as I^2C Fm+	V_{CC} ≥ 4.5 V, I_{OH} = - 4 mA	V_{CC} - 0.5	-	V_{CC}	V	At GPIO
			V_{CC} < 4.5V, I_{OH} = - 3 mA					

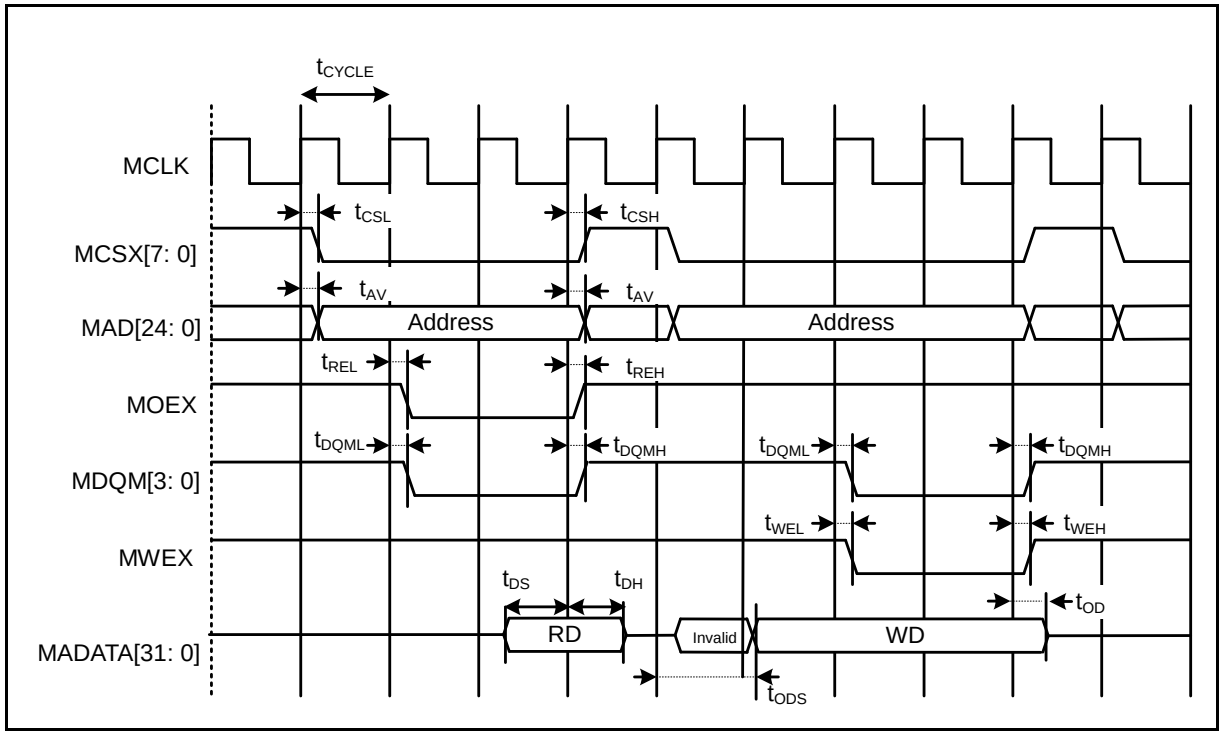
Separate Bus Access Synchronous SRAM Mode

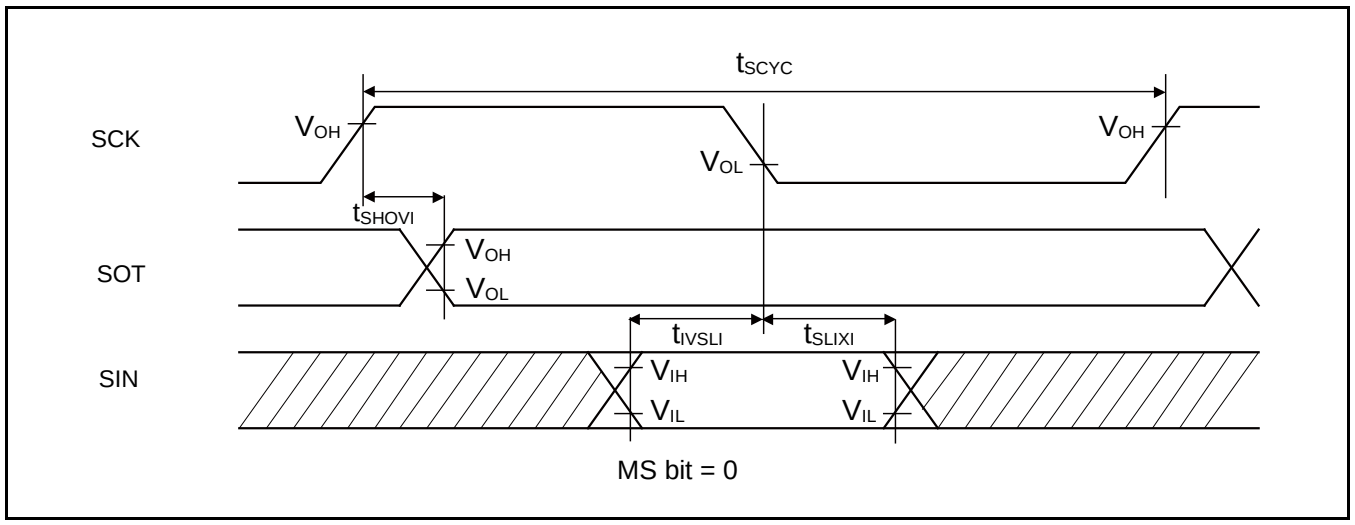
(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Address delay time	t_{AV}	MCLK, MAD[24: 0]	-	1	9	ns	
MCSX delay time	t_{CSL}	MCLK, MCSX[7: 0]	-	1	9	ns	
	t_{CSH}		-	1	9	ns	
MOEX delay time	t_{REL}	MCLK, MOEX	-	1	9	ns	
	t_{REH}		-	1	9	ns	
Data set up →MCLK ↑ time	t_{DS}	MCLK, MADATA[31: 0]	-	19	-	ns	
MCLK ↑ → Data hold time	t_{DH}	MCLK, MADATA[31: 0]	-	0	-	ns	
MWEX delay time	t_{WEL}	MCLK, MWEX	-	1	9	ns	
	t_{WEH}		-	1	9	ns	
MDQM[1: 0] delay time	t_{DQML}	MCLK, MDQM[3: 0]	-	1	9	ns	
	t_{DQMH}		-	1	9	ns	
MCLK ↑ → Data output time	t_{ODS}	MCLK, MADATA[31: 0]	-	MCLK+1	MCLK+18	ns	
MCLK ↑ → Data hold time	t_{OD}	MCLK, MADATA[31: 0]	-	1	18	ns	

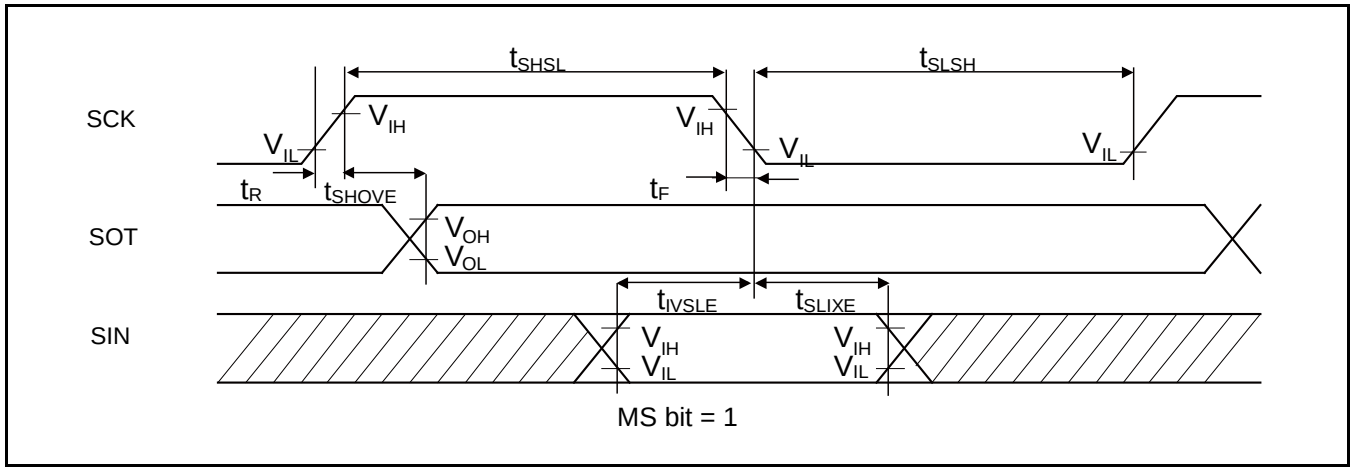
Note:

- *When the external load capacitance C_L = 30 pF*

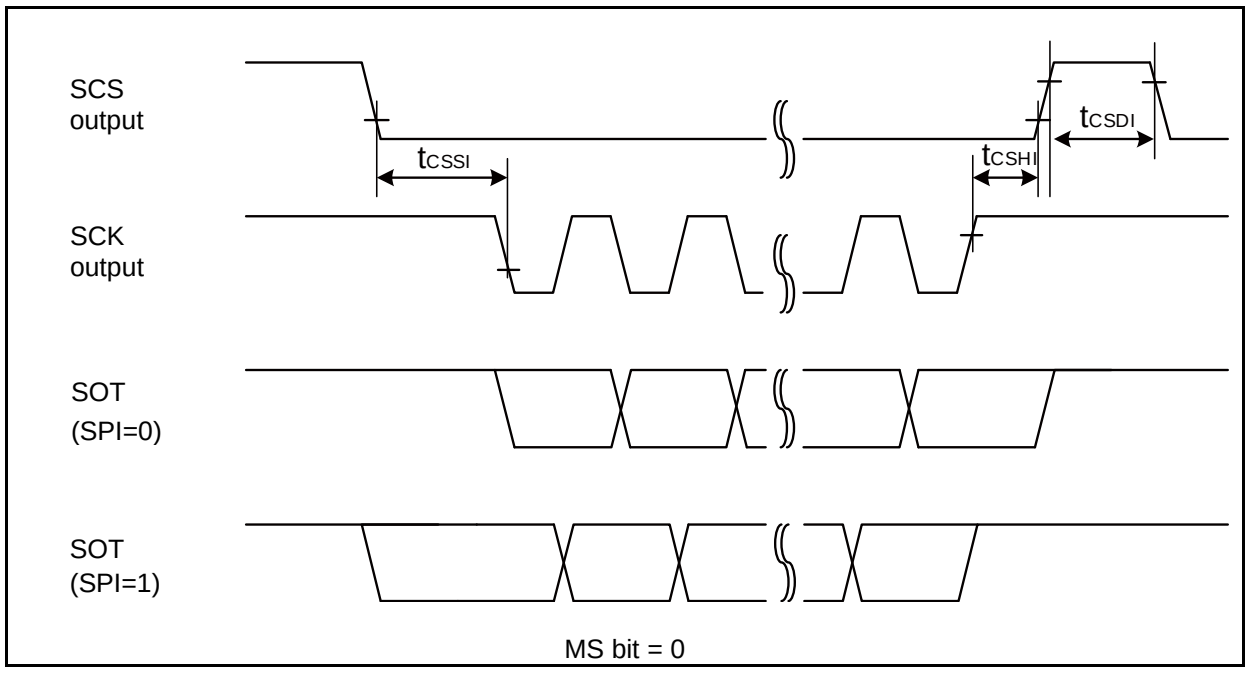


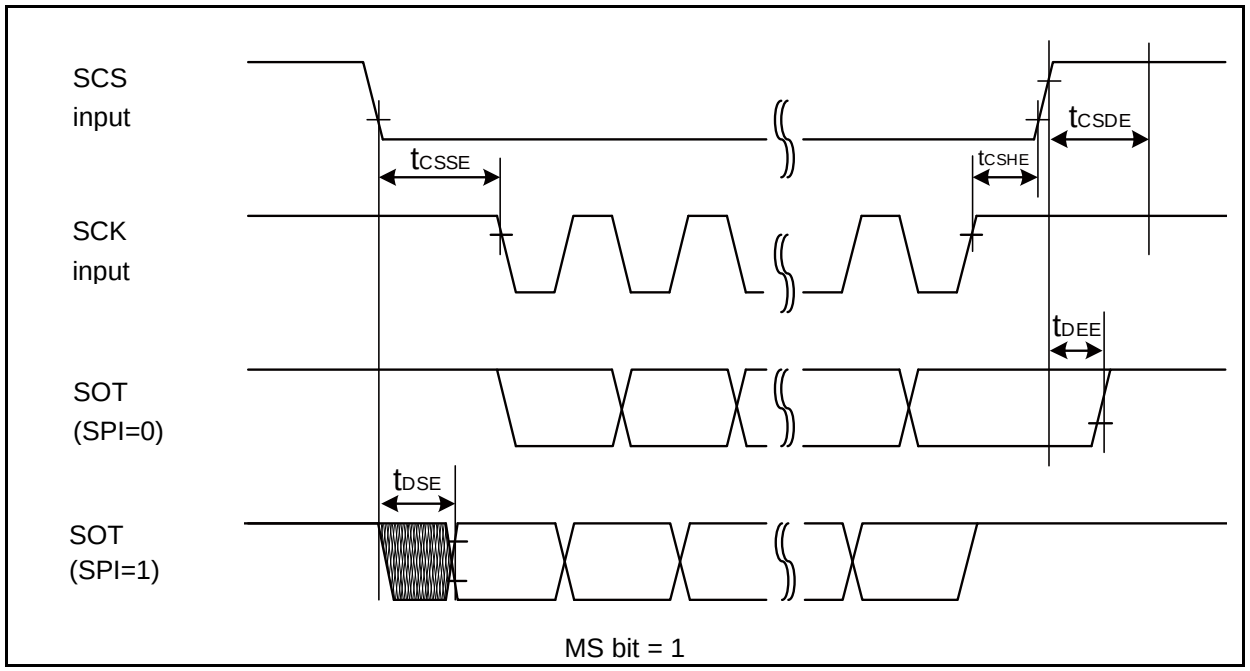


MS bit = 0



MS bit = 1


SCS
output
SCK
output
SOT
(SPI=0)
SOT
(SPI=1)
tCSSI
tCSHI
tCSDI
MS bit = 0


SCS
input
SCK
input
SOT
(SPI=0)
SOT
(SPI=1)
tCSSE
tCSHE
tCSDE
tDEE
tDSE
MS bit = 1

When Using Synchronous Serial Chip Select (SCINV = 0, CSLVL = 0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
			Min	Max	Min	Max	
SCS↑→SCK↓ setup time	t_{CSSI}	Internal shift clock operation	(*1)-50	(*1)+0	(*1)-50	(*1)+0	ns
SCK↑→SCS↓ hold time	t_{CSHI}		(*2)+0	(*2)+50	(*2)+0	(*2)+50	ns
SCS deselect time	t_{CSDI}		(*3)-50 +5t_{CYCP}	(*3)+50 +5t_{CYCP}	(*3)-50 +5t_{CYCP}	(*3)+50 +5t_{CYCP}	ns
SCS↑→SCK↓ setup time	t_{CSSE}	External shift clock operation	3t_{CYCP}+30	-	3t_{CYCP}+30	-	ns
SCK↑→SCS↓ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		3t_{CYCP}+30	-	3t_{CYCP}+30	-	ns
SCS↑→SOT delay time	t_{DSE}		-	40	-	40	ns
SCS↓→SOT delay time	t_{DEE}		0	-	0	-	ns

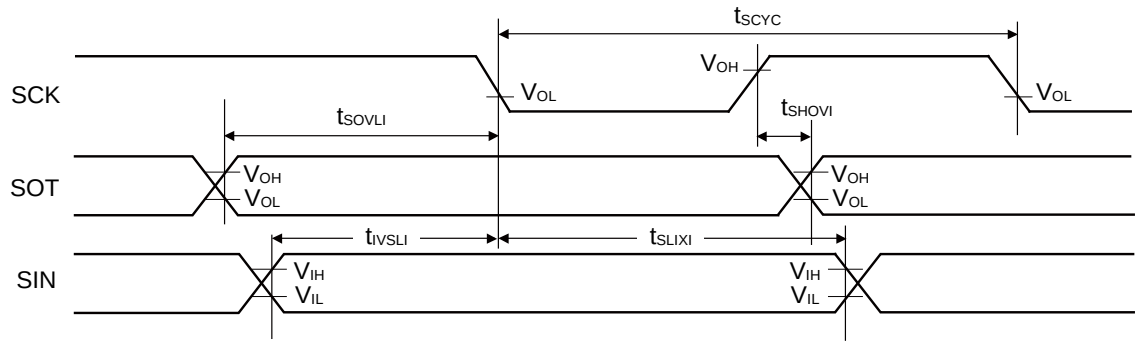
(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]

(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]

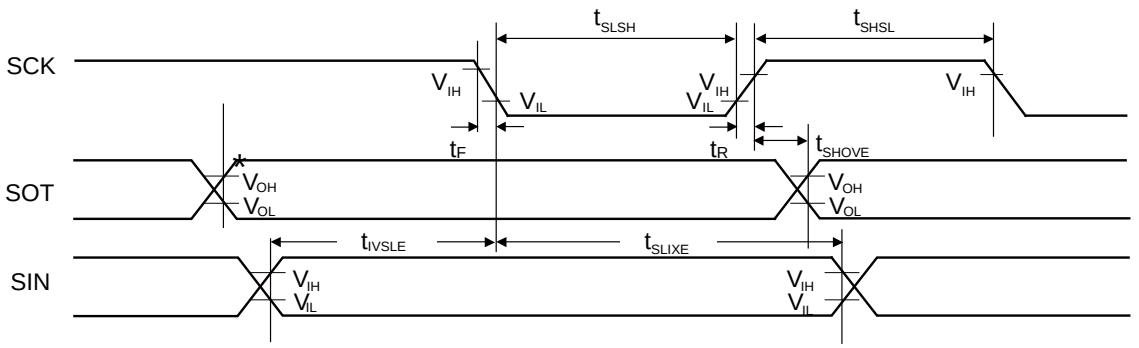
(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 1. S6E2G Series Block Diagram in this data sheet.*
- *For more information about CSSU, CSHD, CSDS, and the serial chip select timing operating clock, see FM4 Family Peripheral Manual Main Part (002-04856).*
- *When the external load capacitance C_L = 30 pF.*



MS bit = 0



MS bit = 1

*: Changes when writing to TDR register

High-Speed Synchronous Serial (SPI = 1, SCINV = 1)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	
Serial clock cycle time	t_{SCYC}	SCKx	Internal shift clock operation	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK↓→SOT delay time	t_{SLOVI}	SCKx, SOTx		- 10	+ 10	- 10	+ 10	ns
SIN→SCK↑ setup time	t_{IVSHI}	SCKx, SINx		14 12.5*	-	12.5	-	ns
SCK↑→SIN hold time	t_{SHIXI}	SCKx, SINx		5	-	5	-	ns
SOT→SCK↑ delay time	t_{SOVHI}	SCKx, SOTx		$2t_{CYCP}$ - 10	-	$2t_{CYCP}$ - 10	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	External shift clock operation	$2t_{CYCP}$ - 5	-	$2t_{CYCP}$ - 5	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK↓→SOT delay time	t_{SLOVE}	SCKx, SOTx		-	15	-	15	ns
SIN→SCK↑ setup time	t_{IVSHE}	SCKx, SINx		5	-	5	-	ns
SCK↑→SIN hold time	t_{SHIXE}	SCKx, SINx		5	-	5	-	ns
SCK fall time	t_F	SCKx		-	5	-	5	ns
SCK rise time	t_R	SCKx		-	5	-	5	ns

Notes:

- *The above characteristics apply to CLK synchronous mode.*
- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 1. S6E2G Series Block Diagram in this data sheet.*
- *These characteristics only guarantee the following pins:*

  No chip select: SIN4_0, SOT4_0, SCK4_0

  Chip select: SIN6_0, SOT6_0, SCK6_0, SCS60_0, SCS61_0, SCS62_0, SCS63_0
- *When the external load capacitance C_L = 30 pF. (for *, when C_L = 10 pF)*

When Using High-Speed Synchronous Serial Chip Select (SCINV = 1, CSLVL = 0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
			Min	Max	Min	Max	
SCS↓→SCK↓ setup time	t_{CSSI}	Internal shift clock operation	(*1)-20	(*1)+0	(*1)-20	(*1)+0	ns
SCK↑→SCS↓ hold time	t_{CSHI}		(*2)+0	(*2)+20	(*2)+0	(*2)+20	ns
SCS deselect time	t_{CSDI}		(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	ns
SCS↑→SCK↑ setup time	t_{CSSE}	External shift clock operation	3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCK↓→SCS↓ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCS↑→SOT delay time	t_{DSE}		-	40	-	40	ns
SCS↓→SOT delay time	t_{DEE}		0	-	0	-	ns

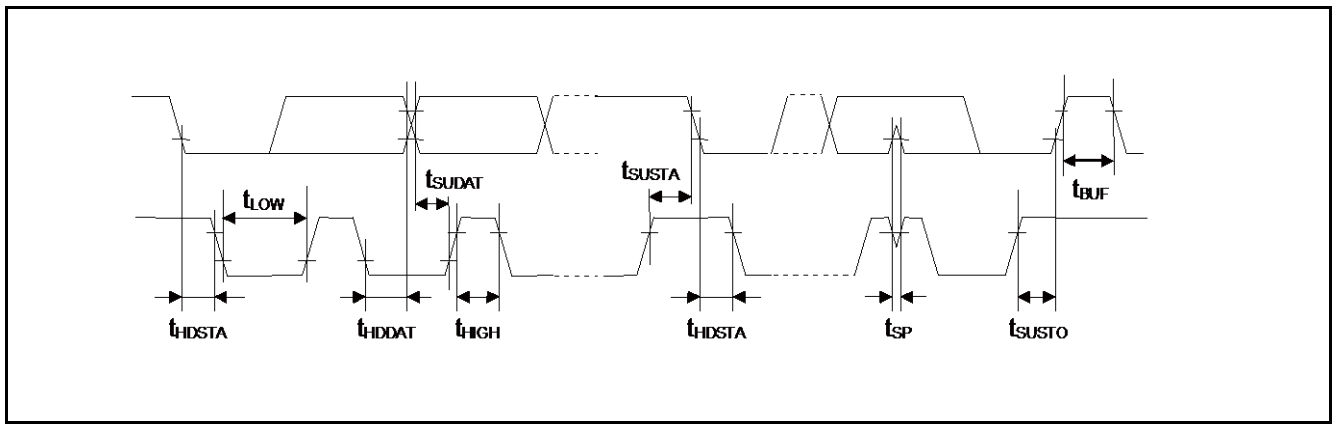
(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]

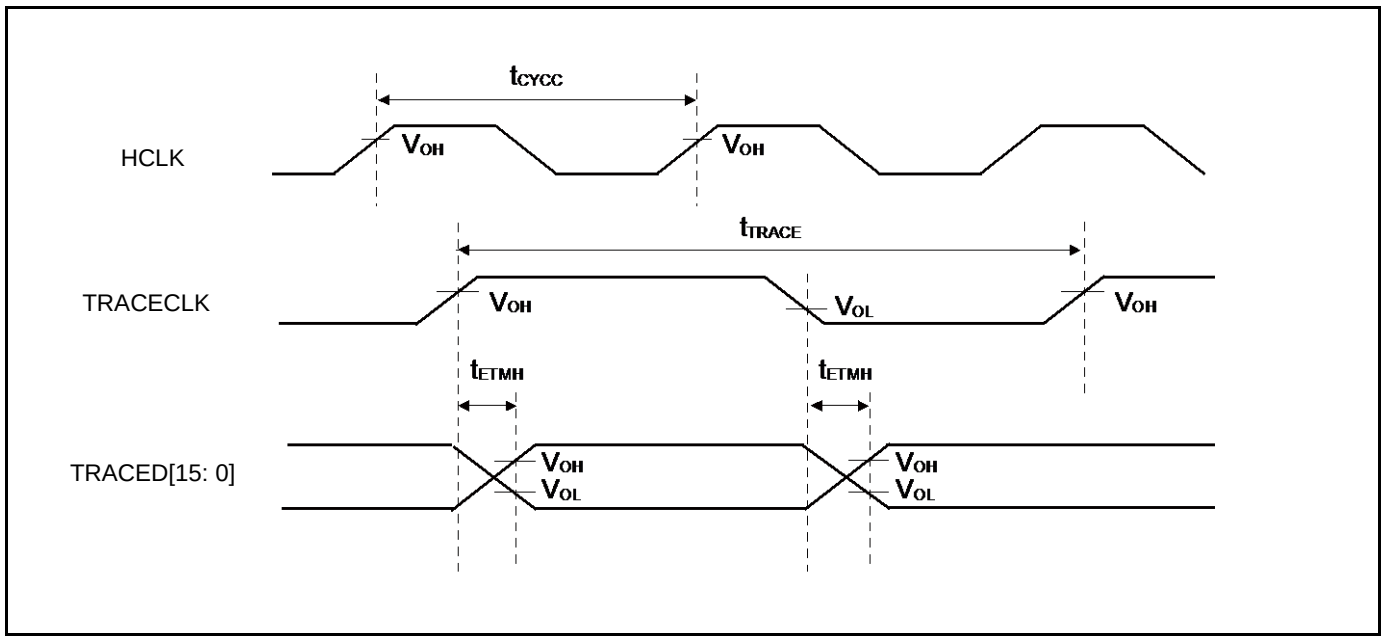
(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]

(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 1. S6E2G Series Block Diagram in this data sheet.*
- *For more information about CSSU, CSHD, CSDS, and the serial chip select timing operating clock, see FM4 Family Peripheral Manual Main Part (002-04856).*
- *When the external load capacitance C_L = 30 pF.*


tLOW
tSUDAT
tSUSTA
tBUF
tHDSTA
tHDDAT
tHIGH
tHDSTA
tSP
tSUSTO

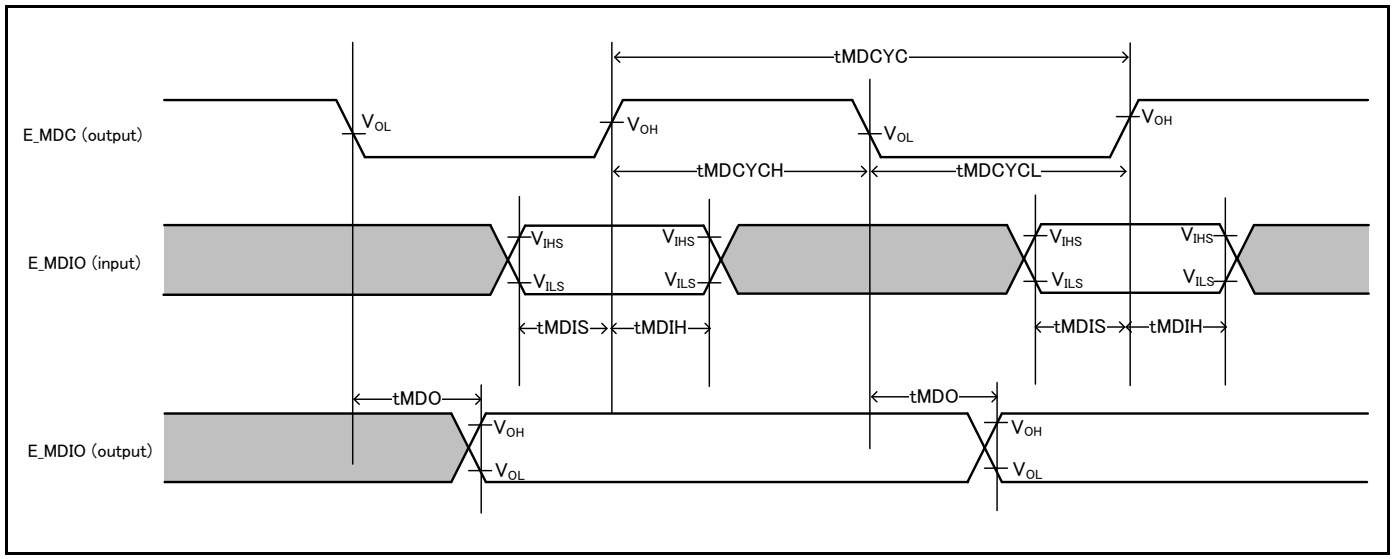

tCYCC
HCLK
VOH
VOH
tTRACE
TRACECLK
VOH
VOL
VOH
tETMH
tETMH
TRACED[15: 0]
VOH
VOL
VOH
VOL

Management Interface

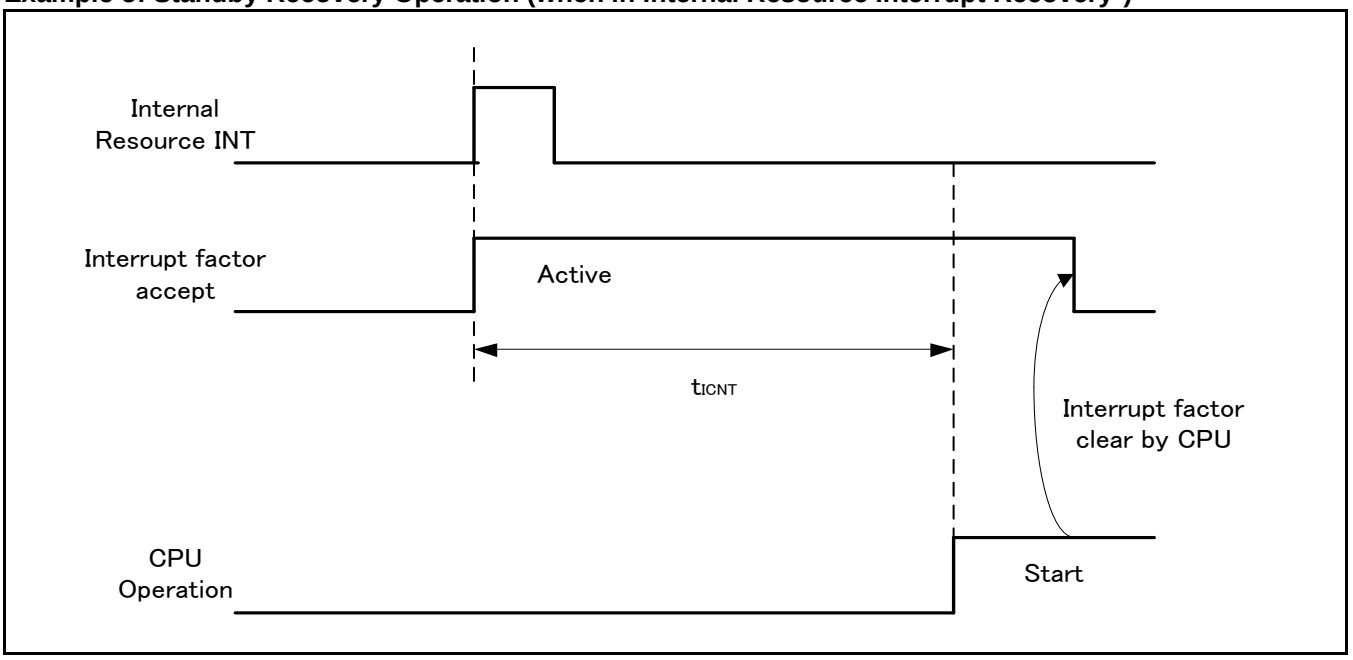
($ETHV_{CC}$ = 3.0V to 3.6V, 4.5V to 5.5V, V_{SS} = 0V, C_L = 25 pF)

Parameter	Symbol	Pin Name	Conditions	Value		Unit
				Min	Max	
Management clock cycle time*	t_{MDCYC}	E_MDC	-	400	-	ns
Management clock High pulse width duty cycle	t_{MDCYCH}	E_MDC	t_{MDCYCH}/t_{MDCYC}	35	65	%
Management clock Low pulse width duty cycle	t_{MDCYCL}	E_MDC	t_{MDCYCL}/t_{MDCYC}	35	65	%
MDC ↓ → MDIO Delay time	t_{MDO}	E_MDIO	-	-	60	ns
MDIO → MDC ↑ Setup time	t_{MDIS}	E_MDIO	-	20	-	ns
MDC ↑ → MDIO Hold time	t_{MDIH}	E_MDIO	-	0	-	ns

*: The clock time should be set to a value greater than the minimum value by setting the Ethernet-MAC setting register.



Example of Standby Recovery Operation (when in Internal Resource Interrupt Recovery*)



*: Depending on the standby mode, interrupt from the internal resource is not included in the recovery cause.

Notes:

- *The return factor is different in each low-power consumption mode. See Chapter 6: Low Power Consumption mode and Operations of Standby modes in FM4 Family Peripheral Manual Main Part (002-04856).*
- *The recovery process is unique for each operating mode. See Chapter 6: Low Power Consumption mode in FM4 Family Peripheral Manual Main Part (002-04856).*

13. Ordering Information

Part Number	Flash	RAM	CAN	Ethernet	SD Card	Crypto	Package
S6E2GM6H0AGV2000A	512 KB	128 KB	✓	✓	✓		Plastic LQFP (0.5 mm pitch), 144 pin (LQS144)
S6E2GM8H0AGV2000A	1 MB	192 KB	✓	✓	✓		
S6E2GM6HHAGV2000A	512 KB	128 KB	✓	✓	✓	✓	
S6E2GM8HHAGV2000A	1 MB	192 KB	✓	✓	✓	✓	
S6E2GM6J0AGV2000A	512 KB	128 KB	✓	✓	✓		Plastic LQFP (0.5 mm pitch), 176 pin (LQP176)
S6E2GM8J0AGV2000A	1 MB	192 KB	✓	✓	✓		
S6E2GM6JHAGV2000A	512 KB	128 KB	✓	✓	✓	✓	
S6E2GM8JHAGV2000A	1 MB	192 KB	✓	✓	✓	✓	
S6E2GK6H0AGV2000A	512 KB	128 KB		✓	✓		Plastic LQFP (0.5 mm pitch), 144 pin (LQS144)
S6E2GK8H0AGV2000A	1 MB	192 KB		✓	✓		
S6E2GK6HHAGV2000A	512 KB	128 KB		✓	✓	✓	
S6E2GK8HHAGV2000A	1 MB	192 KB		✓	✓	✓	
S6E2GK6J0AGV2000A	512 KB	128 KB		✓	✓		Plastic LQFP (0.5 mm pitch), 176 pin (LQP176)
S6E2GK8J0AGV2000A	1 MB	192 KB		✓	✓		
S6E2GK6JHAGV2000A	512 KB	128 KB		✓	✓	✓	
S6E2GK8JHAGV2000A	1 MB	192 KB		✓	✓	✓	
S6E2GH6H0AGV2000A	512 KB	128 KB	✓		✓		Plastic LQFP (0.5 mm pitch), 144 pin (LQS144)
S6E2GH8H0AGV2000A	1 MB	192 KB	✓		✓		
S6E2GH6J0AGV2000A	512 KB	128 KB	✓		✓		Plastic LQFP (0.5 mm pitch), 176 pin (LQP176)
S6E2GH8J0AGV2000A	1 MB	192 KB	✓		✓		
S6E2G36H0AGV2000A	512 KB	128 KB					Plastic LQFP (0.5 mm pitch), 144 pin (LQS144)
S6E2G38H0AGV2000A	1 MB	192 KB					
S6E2G36J0AGV2000A	512 KB	128 KB					Plastic LQFP (0.5 mm pitch), 176 pin (LQP176)
S6E2G38J0AGV2000A	1 MB	192 KB					
S6E2G26H0AGV2000A	512 KB	128 KB		✓			Plastic LQFP (0.5 mm pitch), 144 pin (LQS144)
S6E2G28H0AGV2000A	1 MB	192 KB		✓			
S6E2G26HHAGV2000A	512 KB	128 KB		✓		✓	
S6E2G28HHAGV2000A	1 MB	192 KB		✓		✓	
S6E2G26J0AGV2000A	512 KB	128 KB		✓			Plastic LQFP (0.5 mm pitch), 176 pin (LQP176)
S6E2G28J0AGV2000A	1 MB	192 KB		✓			
S6E2G26JHAGV2000A	512 KB	128 KB		✓		✓	
S6E2G28JHAGV2000A	1 MB	192 KB		✓		✓	